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Notice of Allowability	Application No.	Applicant(s)	•
	10/064,500 Examiner	BARMATZ ET AL. Art Unit	
	Quang T Van	3742	_
The MAILING DATE of this communication app All claims being allowable, PROSECUTION ON THE MERITS Is herewith (or previously mailed), a Notice of Allowance (PTOL-88 NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT I of the Office or upon petition by the applicant. See 37 CFR 1.37	S (OR REMAINS) CLOSED ir 5) or other appropriate commu RIGHTS. This application is s	nthis application. If not included unication will be mailed in due course. THIS	; tive
1. \boxtimes This communication is responsive to <u>Amendment filed 4/</u>	<u>′22/2004</u> .		
2. The allowed claim(s) is/are <u>1-35</u> .			
3. \boxtimes The drawings filed on <u>22 July 2002</u> are accepted by the l	Examiner.		
 4. ☐ Acknowledgment is made of a claim for foreign priority a) ☐ All b) ☐ Some* c) ☐ None of the: 1. ☐ Certified copies of the priority documents hat 2. ☐ Certified copies of the priority documents hat 3. ☐ Copies of the certified copies of the priority of International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE noted below. Failure to timely comply will result in ABANDON THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 5. ☐ A SUBSTITUTE OATH OR DECLARATION must be sub INFORMAL PATENT APPLICATION (PTO-152) which g 6. ☐ CORRECTED DRAWINGS (as "replacement sheets") m (a) ☐ including changes required by the Notice of Draftspet (b) ☐ including changes required by the attached Examine Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR each sheet. Replacement sheet(s) should be labeled as such in the department of the department o	ve been received. ve been received in Application documents have been received documents application. In the header according to 37 CE docsit of BIOLOGICAL MAT	on No d in this national stage application from the d in this national stage application from the a reply complying with the requirements AMINER'S AMENDMENT or NOTICE OF redeclaration is deficient. W (PTO-948) attached In the Office action of the drawings in the front (not the back) of FR 1.121(d). ERIAL must be submitted. Note the	
Attachment(s) 1. ☐ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☐ Information Disclosure Statements (PTO-1449 or PTO/SE Paper No./Mail Date 4. ☐ Examiner's Comment Regarding Requirement for Deposi of Biological Material	3) 6. ☐ Interview S Paper No. 3/08), 7. ☒ Examiner's	Informal Patent Application (PTO-152) Informal Patent Application (PTO	

EXAMINER'S AMENDMENT

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Attorney Bing Ai (Reg. No. 43,312) on July 2, 2004.

The application has been amended as follows:

In claim 24, at line 11, after wherein, insert -- said first and said second surfaces each includes a metal, --

In claim 26, at line 11, after wherein, insert -- said first and said second surfaces each includes a metal, --

REASON FOR ALLOWANCE

2. The following is an examiner's statement of reasons for allowance: allowance of claims 1-35 is indicated because the prior art of record does not show or suggest placing a first substrate with a first metal surface part that has better microwave absorption than said first substrate, against a second substrate with a second metal surface part that has better microwave absorption than said second substrate and applying microwave energy to the first and second surface parts to bond the first substrate to the second substrate as recited in claims 1, 7-8, 21, 23, 25; placing a first substrate with a first surface part that has better microwave absorption than said first

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substrate, against a second substrate with a second surface part that has better microwave absorption than said second substrate, applying microwave energy to the first and second surface parts to bond the first substrate to the second substrate, wherein the first substrate is placed on top of the second substrate and is held only by gravity during bonding as recited in claims 2, 5, 6, 9-10; placing a first substrate with a first surface part that has better microwave absorption than said first substrate, against a second substrate with a second surface part that has better microwave absorption than said second substrate, applying microwave energy to the first and second surface parts to bond the first substrate to the second substrate, wherein said bonding includes hermetically sealing a cavity as recited in claims 3-4; placing a first substrate of a first material, having a first area defined within a perimeter of a second material, against a second substrate, of the third material, said second substrate also having a second area defined within a perimeter of a fourth material, and wherein said first and third materials are poorer absorbers of microwaves than said second and fourth materials and the step of applying microwaves to an area of said first substrate and said second substrate to bond said second material to said fourth material as recited in claims 11-20; placing a first substrate with a first surface part that has better microwave absorption than said first substrate, against a second substrate with a second surface part that has better microwave absorption than said second substrate, said first and second surfaces coupled together to define an area of connection therebetween, wherein said material of said first substrate is semiconductor material as recited in claim 22; placing a first substrate with a first surface part that has better microwave absorption than said first

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substrate, against a second substrate with a second surface part that has better microwave absorption than said second substrate, said first and second surfaces coupled together to define an area of connection therebetween, wherein said first and said second surfaces each includes a metal, said metal has a thickness within an order of magnitude of the skin dept of the first and second surfaces as recited in claim 24; placing a first substrate with a first surface part that has better microwave absorption than said first substrate, against a second substrate with a second surface part that has better microwave absorption than said second substrate, said first and second surfaces coupled together to define an area of connection, wherein said area of connection forms a closed perimeter, which defines a hermetically sealed chamber as recited in claims 26-27; and the step of bringing a first semiconductor substrate with a first metal film into contact with a second semiconductor substrate with a second metal film, where both of said first and second metal films are less than an order of magnitude thicker than the skin depth of the metal as recited in claims 28-34.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

3. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Quang T Van whose telephone number is 703-306-9162. The examiner can normally be reached on 8:00Am 7:00Pm M-Th.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Robin Evans can be reached on 703-305-5766. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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July 2, 2004

Quang T Van

Primary Examiner

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